	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	1713	257/777	USPAT	2003/10/17 15:03
2	BRS	1	"4398235".PN.	USPAT	2003/10/16 23:24
3	BRS	1	"4570337".PN.	USPAT	2003/10/16 23:24
4	BRS	1	"4663652".PN.	USPAT	2003/10/16 23:24
5	BRS	1	"4663652".PN.	USPAT	2003/10/16 23:24
6	BRS	1	"5239198".PN.	USPAT	2003/10/17 13:14
7	BRS	1	"5815372".PN.	USPAT	2003/10/17 13:14
8	BRS	1	"6080931".PN.	USPAT	2003/10/17 13:14
9	BRS	1	"6104088".PN.	USPAT	2003/10/17 13:14
10	BRS	146	257/685	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:06
11	BRS	460	257/686	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:06
12	BRS	313	257/777	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:07
13	BRS	309	361/760	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:07
14	BRS	232	438/108	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:07
15	BRS	652	438/109	USPAT	2003/10/17 15:07

	Type	Hits	Search Text	DBs	Time Stamp
16	BRS	1392	438/108	USPAT	2003/10/17 15:08
17	BRS	862	257/685	USPAT	2003/10/17 15:09
18	BRS	1806	257/686	USPAT	2003/10/17 15:10
19	BRS	2928	361/760	USPAT	2003/10/17 15:11
20	BRS	2034	(semiconductor or die or chip or IC) and lead and (ball or bump) and protective near (layer or film)	USPAT	2003/10/17 17:08
21	BRS	128	((semiconductor or die or chip or IC) and lead and (ball or bump) and protective near (layer or film)) and (semiconductor or die or chip or IC) and (ball or bump) and protective near (layer or film) with lead	USPAT	2003/10/17 18:43
22	BRS	29	(semiconductor or die or chip or IC) and (ball or bump) with protective near (layer or film) with lead	USPAT	2003/10/17 18:45
23	BRS	2	(semiconductor or die or chip or IC) and (ball or bump) with insulating near coat$3 near (layer or film) with lead	USPAT	2003/10/17 18:46
24	BRS	113	(semiconductor or die or chip or IC) and (ball or bump) with insulating near (layer or film) with lead	USPAT	2003/10/17 19:40
25	BRS	234	(semiconductor or die or chip or IC) and (ball or bump) with insulating with lead	USPAT	2003/10/17 19:56
26	BRS	1532	(semiconductor or die or chip or IC) and (ball or bump) and insulating with lead	USPAT	2003/10/17 21:27

	Type	Hits	Search Text	DBs	Time Stamp
27	BRS	0	((semiconductor or die or chip or IC) and (ball or bump) and insulating with lead) and (semiconductor or die or chip or IC) and (ball or bump) and insulating with form$3 with on with lead	USPAT	2003/10/17 19:57
28	BRS	1298	((semiconductor or die or chip or IC) and (ball or bump) and insulating with lead) not ((semiconductor or die or chip or IC) and (ball or bump) with insulating with lead)	USPAT	2003/10/17 19:58
29	BRS	1	"5134093".PN.	USPAT	2003/10/17 20:45
30	BRS	1	"5213996".PN.	USPAT	2003/10/17 20:45
31	BRS	1	"5330935".PN.	USPAT	2003/10/17 20:45
32	BRS	1	"5334544".PN.	USPAT	2003/10/17 20:45
33	BRS	1	"5338393".PN.	USPAT	2003/10/17 20:45
34	BRS	1	"4509096".PN.	USPAT	2003/10/17 20:46
35	BRS	1	"5081562".PN.	USPAT	2003/10/17 20:46
36	BRS	1	"5095627".PN.	USPAT	2003/10/17 20:46
37	BRS	4	"5595934"	USPAT	2003/10/17 20:48
38	BRS	5	"5291374"	USPAT	2003/10/17 20:48
39	BRS	1026	257/666 and lead with (insulat$3 or dielectric or protective)	USPAT	2003/10/17 20:49
40	BRS	465	257/666 and lead with (insulat$3 or dielectric or protective or reisit$3) and (ball or bump)	USPAT	2003/10/17 21:18
41	BRS	15932	polyamide with polyimide	USPAT	2003/10/17 21:19

	Type	Hits	Search Text	DBs	Time Stamp
42	BRS	8106	polyamide near polyimide	USPAT	2003/10/17 21:18
43	BRS	1589	"257" and polyamide with polyimide	USPAT	2003/10/17 21:20
44	BRS	314	(semiconductor or die or chip or IC) and (ball or bump) and insulating with lead	JPO	2003/10/17 21:27
45	BRS	42	((semiconductor or die or chip or IC) and (ball or bump) and insulating with lead) and polyimide	JPO	2003/10/17 21:50
46	BRS	0	"5276351"	JPO	2003/10/17 21:50
47	BRS	11	"5276351"	USPAT	2003/10/17 21:52
48	BRS	2229	lead with polyimide	USPAT	2003/10/17 21:53
49	BRS	155	(lead with polyimide) and lead with polyimide with coating	USPAT	2003/10/17 21:57
50	BRS	2229	(lead with polyimide) and lead with polyimide	USPAT	2003/10/17 21:57
51	BRS	901	(lead with polyimide) and (ball or bump)	USPAT	2003/10/17 21:58